

RECEIVED
CENTRAL FAX CENTER
AUG 22 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Daniel F. Sievenpiper)	Examiner:	Tai, Nguyen
Serial No.	10/728,506)	Art Unit:	3729
Filed:	12/5/2003)	Our Ref:	B-4046DIV 621280-9
For:	"Molded High Impedance Surface and Method of ...")	Date:	August 22, 2006
)	Re:	<i>Response After Final</i>
)	VIA TELEFAX	571-273-8300
)	Number of Pages:	6

RESPONSE

Box AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This paper is filed in response to the final rejection issued with respect to the above-identified US Patent Application on June 20, 2006.

Applicant's remarks appear on Page 2 of this Response.